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PATENT

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#131  
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OCTOBER 2, 2001  
Date

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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant	: Tongbi Jiang	Attorney Docket No.:	500182.01 (660073.774)
Serial No.	: 09/365,356	Group Art Unit	: 2813
Filed	: July 30, 1999	Examiner	: Nema O. Berezny
Title	: METHOD AND STRUCTURE FOR MANUFACTURING IMPROVED YIELD SEMICONDUCTOR PACKAGED DEVICES		

Box Non-Fee Amendment  
Commissioner of Patents  
Washington, DC 20231

AMENDMENT

Sir:

Please amend the above-captioned patent application as follows:

In the Claims:

Please cancel claims 4, 16, and 46-49.

Please amend claims 1, 5-7, 9-11, 17-18, and 42-43 as follows:

1. (Amended) A semiconductor device package, comprising:
- a semiconductor die having a first surface on which an integrated circuit and at least one electrically conductive bond pad are fabricated;
  - at least one electrically conductive external terminal;
  - an interposer having a die attach surface and an external surface opposite of the die attach surface disposed in between the semiconductor die and the at least one external